

FIG. 1A

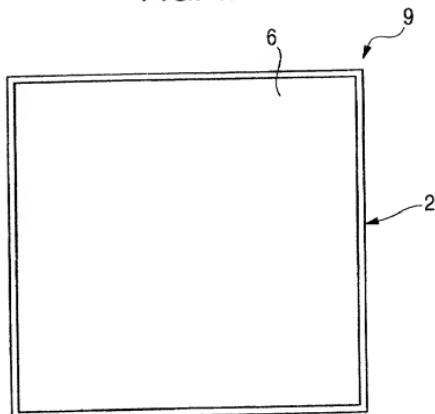
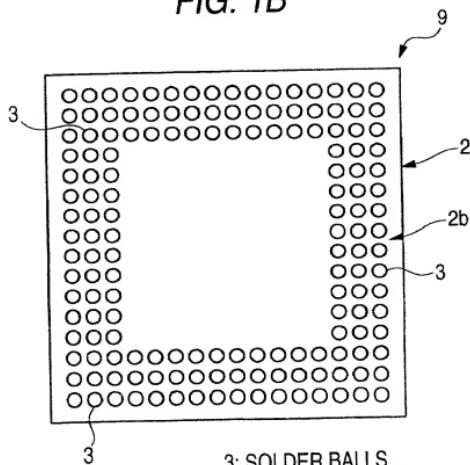


FIG. 1B

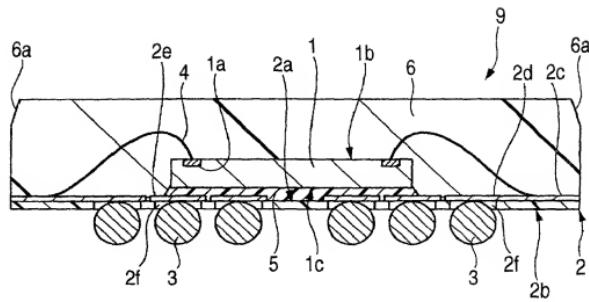


3: SOLDER BALLS

6: SEALED PORTION

9: CSP (SEMICONDUCTOR DEVICE)

FIG. 2



1a: PADS (SURFACE ELECTRODES)

2c: CONNECTION TERMINALS (ELECTRODES)

FIG. 3A

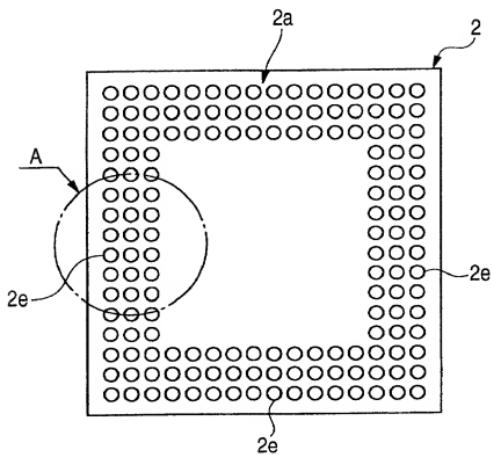


FIG. 3B

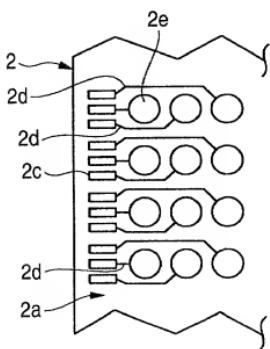
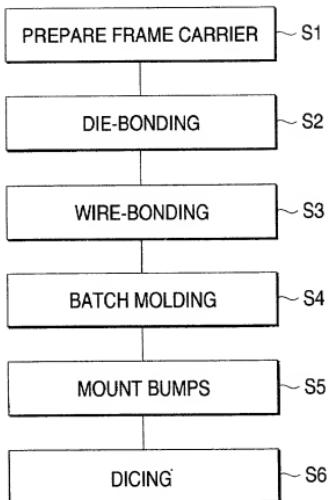


FIG. 4



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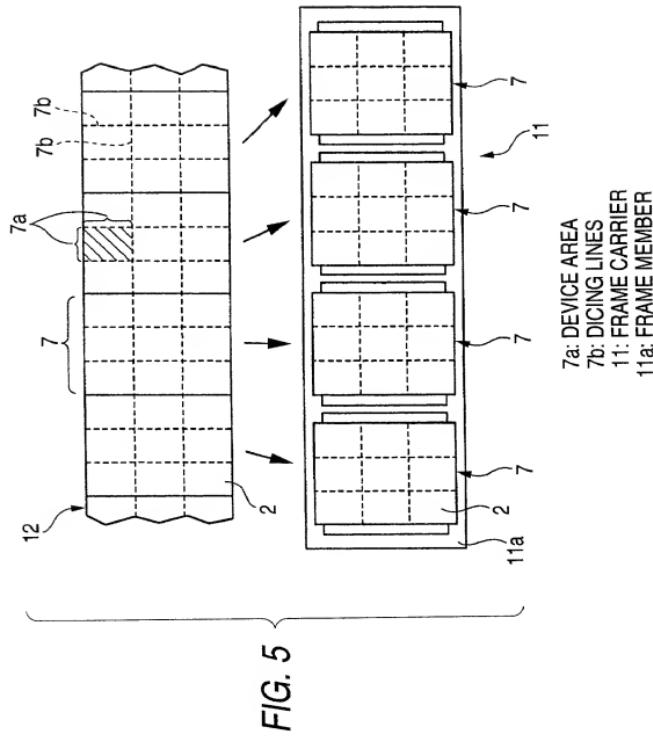


FIG. 6

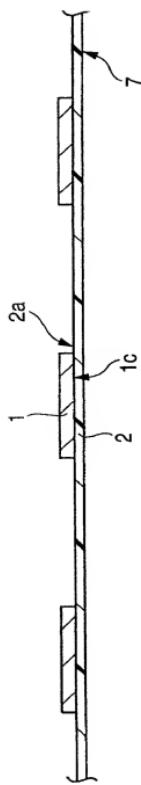


FIG. 7

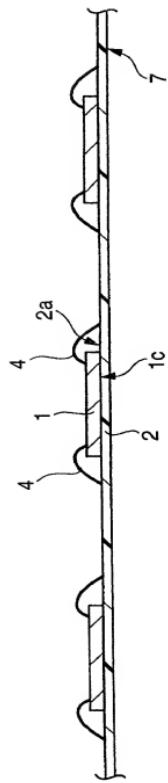


FIG. 8A

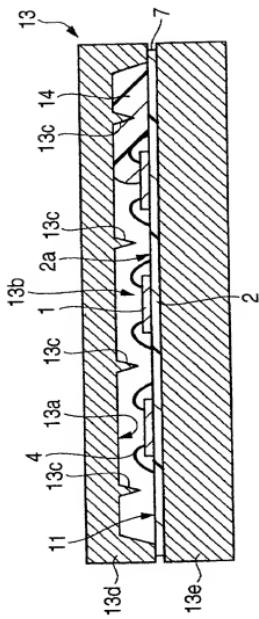


FIG. 8B

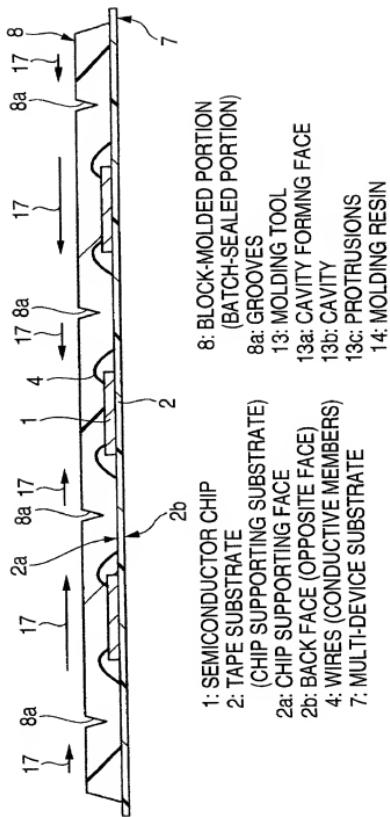
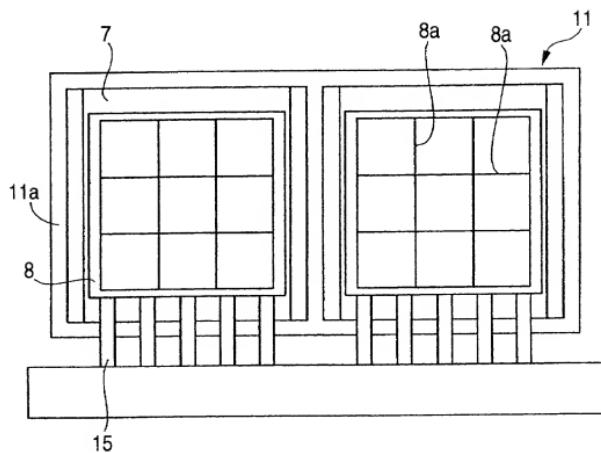


FIG. 9



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FIG. 10

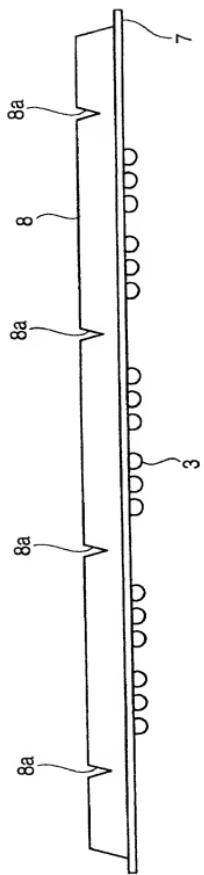


FIG. 11A

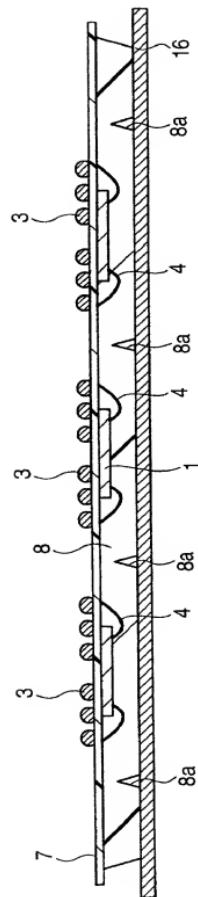


FIG. 11B

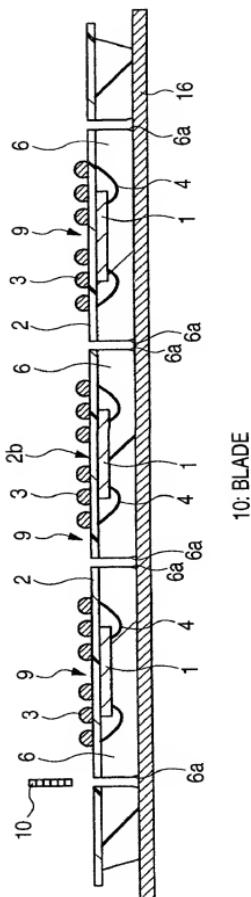


FIG. 12

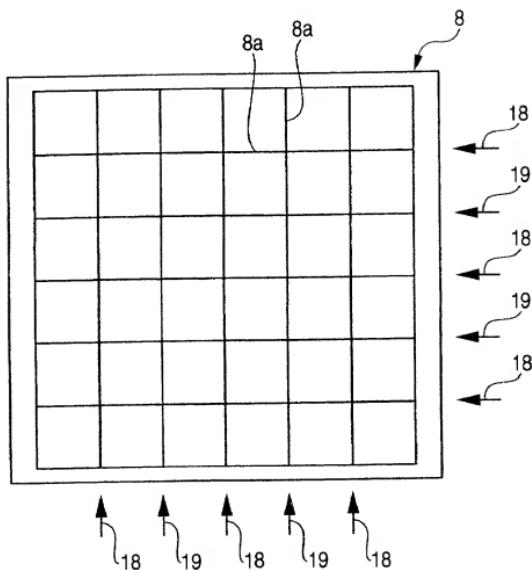


FIG. 13

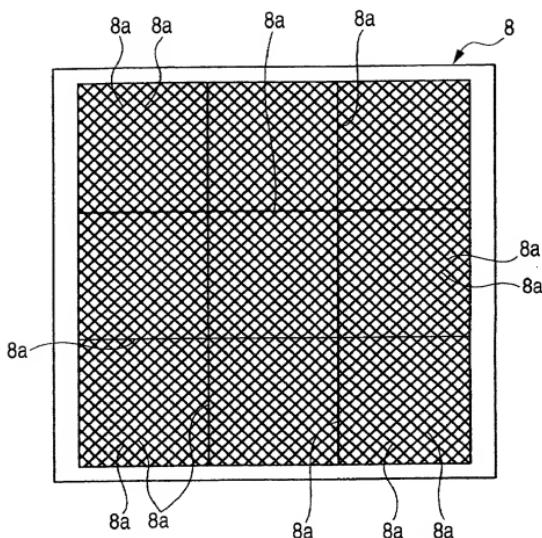


FIG. 14

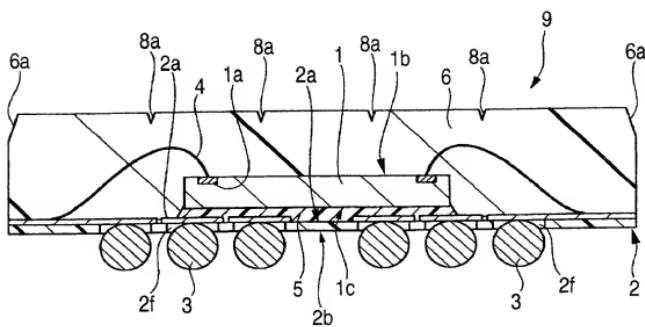


FIG. 15

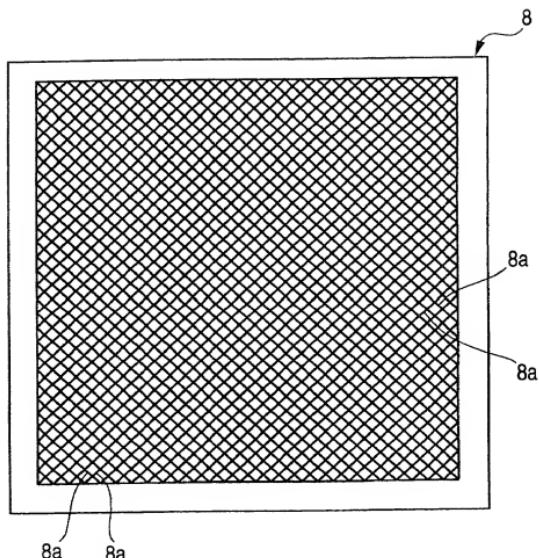
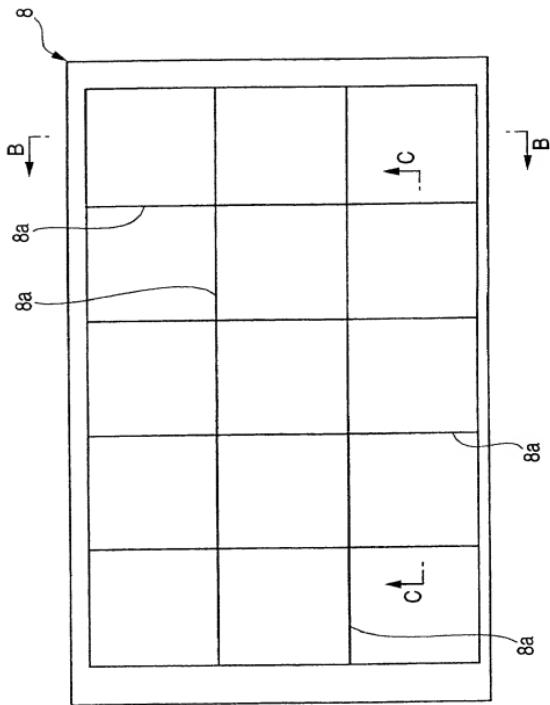


FIG. 16



T3E2800 T59nE6600

FIG. 17A

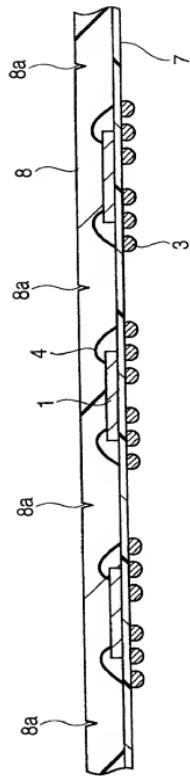


FIG. 17B

